Doc. No. : LITD 05 (23249) **IS/IEC 60068-2-21: 2021**

[Superseding IS 9000 (Part 19/Section 1 to 5):1986]

भारतीय मानक

पर्यावरण परीक्षण

भाग 2 परीक्षण अनुभाग 21 परीक्षण U: अंतक और पूर्णकीय आरोहण युक्तियों की मजबूती

Indian Standard

Environmental Testing

Part 2 Tests
Section 21 Test U: Robustness of Terminations and Integral Mounting Devices

ICS 19.040;31.190

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NEW DELHI 110002

2024 Price Group

Semiconductor Devices Components and Electronic Assembly Technology Sectional Committee, LITD 05

NATIONAL FOREWORD

This Indian Standard (Part 2/Section 21) which is identical with IEC 60068-2-21:2021 'Environmental testing - Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices' issued by the International Electrotechnical Commission (IEC) was adopted by the Bureau of Indian Standards on recommendation of the Semiconductor Devices Components and Electronic Assembly Technology Sectional Committee and approval of the Electronics and Information Technology Division Council.

IS 9000 (Part 19/Sec 1 to 5) was published in 1987 and was identical to IEC 60068-2-21:1983. This superseding of Standard is being done to align it with the latest version of IEC 60068-2-21: 2021. On publication of this Indian Standard (Part 2/Sec 21), IS 9000 (Part 19/Sec 1 to 5): 1986 stands withdrawn.

The text of IEC Standard has been approved as suitable for publication as an Indian Standard without deviations. Certain terminologies and conventions are, however, not identical to those used in Indian Standards. Attention is particularly drawn to the following:

- a) Wherever the words 'International Standard' appear referring to this standard, they should be read as 'Indian Standard'.
- b) Comma (,) has been used as a decimal marker, while in Indian Standards, the current practice is to use a point (.) as the decimal marker.

In this adopted standard, reference appears to certain International Standards for which Indian Standards also exist. The corresponding Indian Standards, which are to be substituted in their respective places, are listed below along with their degree of equivalence for the editions indicated:

International Standards	Corresponding Indian Standards	Degree of Equivalence
IEC 60068-1:2013 Environmental testing – Part 1: General and guidance	IS/IEC 60068-1 : 2013 Environmental Testing Part 1 General and Guidance	Identical
IEC 60068-2-58:2015 Environmental testing – Part 2- 58: Tests – Test Td – Test methods for solderability, resistance to dissolution of	IS/IEC 60068-2-58: 2015 Environmental testing Part 2 Tests Section 58 Test Td: Test methods for solderability resistance to dissolution of metallization and to	-do-

metallization and to soldering heat of surface mounting devices (SMD) soldering heat of surface mounting devices SMD

The technical committee has reviewed the provisions of the following International Standard referred in this adopted standard and has decided that it is acceptable for use in conjunction with this standard:

International Standard	Title
IEC 60194-2	Printed board design, manufacture and assembly – Vocabulary – Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies
IEC 61191-2	Printed board assemblies – Part 2: Sectional specification – Requirements for surface mount soldered assemblies

For the purpose of deciding whether a particular requirement of this standard is complied with, the final value, observed or calculated, expressing the result of a test or analysis, shall be rounded off in accordance with IS 2: 2022 'Rules for rounding off numerical values (second revision)'. The number of significant places retained in the rounded off value should be the same as that of the specified value in this standard.